

Remarks

Claims 15 and 27 have been canceled without prejudice or disclaimer. Claims 13 and 25 have been amended. Claims 37 through 62 have been added. Claims 13-14, 16-26, and 28-62 are currently pending in this application.

No new matter has been inserted. Support for the amendments to claims 13 and 25 can be found in the specification at p. 6, lines 31-33, and p. 8, line 8, respectively. Support for new claims 37 and 38 can be found in the specification at least at p. 3 line 36 through p. 4, line 2 and p. 6, lines 31-33. Support for new claim 39 can be found in the specification at least at p. 3, lines 26-30 and p. 4, lines 23-25. Support for new claims 40-49 can be found in claims 14-24 respectively. Support for new claim 50 can be found in the specification at p. 6, lines 31-33. Support for new claim 51 can be found in the specification at p. 13, line 26, through p. 14, line 24. Support for new claim 52 can be found in claim 26 and support for new claims 53-61 can be found in claims 28-36 respectively. Support for new claim 62 can be found in the specification at least at p. 3 line 36 through p. 4, line 2 and p. 6, lines 31-33.

Reconsideration is respectfully requested in view of the above amendments and following remarks.

35 U.S.C. § 102 – Wright et al.

The office action rejected claims 13-15, 25-28 under 35 U.S.C. § 102(b) as being anticipated by Wright et al. (USPN 3,527,665). The applicants respectfully traverse this rejection.

Wright discloses the production of copper-clad laminates for printed circuit boards made by baking a film of polyphenylene oxide resin onto the copper to be laminated and then laminating the resultant product to a base containing a thermosetting resin. However, Wright does not disclose thermal-resistant synthetic fibers intersecting each other forming intersections, wherein the thermal-resistant synthetic fibers are bound with the inorganic binder at the intersections as required by independent claims 13, 25, 39, and 51. Therefore, at least for this

reason, claims 13, 25, 39, and 51 are not anticipated by Wright. As the rest of the pending claims are dependent on one of claims 13, 25, 39, or 51, they are also not anticipated. Withdrawal of this rejection is respectfully requested.

35 U.S.C. § 103 – EP 807703 and Nakatani

The office action rejected claims 13, 18, 19, and 25-36 under 35 U.S.C. § 103(a) as being unpatentable over EP 807703 in view of Nakatani (USPN 5,888,627). The applicants respectfully traverse this rejection.

EP 807703 discloses a nonwoven fabric cloth substrate with superior insulating properties that is useful for printed wiring boards and that is impregnated with a resin varnish. As conceded by the Examiner, EP 807703 is silent about an inorganic binder. Therefore, EP 807703 does not disclose thermal-resistant synthetic fibers intersecting each other forming intersections, wherein the thermal-resistant synthetic fibers are bound with the inorganic binder at the intersections as required by independent claims 13, 25, 39, and 51.

Nakatani does not cure the deficiencies of EP 807703. Nakatani discloses a printed circuit board comprising a plurality of sheet substrates consisting of resin component layers containing an inorganic insulating filler formed onto both side of an organic nonwoven fabric. However, Nakatani does not disclose thermal-resistant synthetic fibers bound with an inorganic binder at the intersections as required by independent claims 13, 25, 39, and 51. In fact, since the inorganic filler of Nakatani is not melted during the manufacturing process, it cannot bind the fibers. Therefore, the combination of EP 807703 and Nakatani does not teach or suggest the invention as claimed in claims 13, 25, 39, and 51. As the rest of the pending claims are dependent on one of claims 13, 25, 39, or 51, they are also not obvious over EP 807703 in view of Nakatani. For at least these reasons, applicants respectfully request that this rejection be withdrawn.

Conclusion

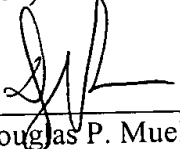
With the above amendments and remarks, Applicants believe that the claims pending in this patent application are in condition for allowance. Favorable consideration is respectfully requested. If any further questions arise, the Examiner is invited to contact Applicants' representative at the number listed below.

Respectfully submitted,

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